



AF/IFW

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Applicant:

Joseph M. Steigerwald

Serial No.: 10/722,801

Filed: November 26, 2003

For: Electrochemically Polishing Conductive
Films on Semiconductor Wafers

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Art Unit: 2815

Examiner: Sheila V. Clark

Atty Docket: ITL.0947US
P15971

Assignee: Intel Corporation

Mail Stop AF
Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

REPLY TO FINAL REJECTION

Sir:

In response to the final rejection mailed April 19, 2005, please amend the above-referenced patent application as follows:

9/2/05
OK/steiger
SVC

Date of Deposit: May 4, 2005

I hereby certify under 37 CFR 1.8(a) that this correspondence is being deposited with the United States Postal Service as **first class** mail with sufficient postage on the date indicated above and is addressed to the Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450.

Cynthia L. Hayden
Cynthia L. Hayden



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ENTERED
By
RCE
6-17-05
V/S

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